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PATENT ABSTRACTS OF JAPAN

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(43) Date of application publication: **30.03.99**(71) Applicant: **MITSUI HIGH TEC INC**

(84) Designated contracting states:

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(74) Representative:

(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a highly reliable semiconductor device which can deal with enhancement of the heat dissipation properties and electric characteristics and the requirements of small, lightweight multi-terminal semiconductor device.

SOLUTION: The semiconductor device 10 comprises a first interposer 14 on which first and second conductor circuit patterns 12, 13 are formed and a second interposer 17 on which third and fourth conductor circuit patterns 15, 16 are formed are bonded formed, respectively, to the surface and backside of a semiconductor element 11 through an example of first and second insulating adhesives 18, 19, i.e., liquid elastomer resins 18a, 19a. The semiconductor device 10 further comprises an example of a plurality of external connection terminals 21, i.e., solder balls 21a, in the form of a

